

Title	金属-半導体界面層あるいは絶縁体-半導体界面層を用いたAlGa <sub>N</sub> /Ga <sub>N</sub> デバイスの閾値電圧制御
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Citation	
Issue Date	2024-06
Type	Thesis or Dissertation
Text version	ETD
URL	<a href="http://hdl.handle.net/10119/19335">http://hdl.handle.net/10119/19335</a>
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# Abstract

We have systematically investigated effects of metal-semiconductor or insulator-semiconductor interfacial layers (ILs) in AlGaIn/GaN devices, where  $\text{AlO}_x$ ,  $\text{TiO}_x$ , or  $\text{NiO}_x$  is employed as an IL. From capacitance-voltage characteristics of metal/IL/AlGaIn/GaN devices with a metal-semiconductor IL between the gate metal and AlGaIn, it is shown that the IL modulates the threshold voltage  $V_{\text{th}}$ , attributed to the vacuum level step induced by the dipole of the IL. We find negative vacuum level steps for  $\text{AlO}_x$  and  $\text{TiO}_x$  ILs, and positive for  $\text{NiO}_x$ , from which the IL dipole density is estimated for each IL material. The two-dimensional electron gas carrier concentration in the metal/IL/AlGaIn/GaN devices is also modulated by the vacuum level step. Furthermore, X-Ray photoelectron spectroscopy of the IL/AlGaIn interfaces suggest a formation of NiGa in the  $\text{NiO}_x$ /AlGaIn interface. On the other hand, from capacitance-voltage characteristics of metal/ $\text{Al}_2\text{O}_3$ /IL/AlGaIn/GaN devices with an insulator-semiconductor IL between  $\text{Al}_2\text{O}_3$  and AlGaIn, the fixed charge density of the  $\text{Al}_2\text{O}_3$ /IL/AlGaIn interface is evaluated by the  $\text{Al}_2\text{O}_3$  thickness dependence of  $V_{\text{th}}$ . For  $\text{AlO}_x$  and  $\text{TiO}_x$  ILs, the fixed charge density is higher than that of the  $\text{Al}_2\text{O}_3$ /AlGaIn interface with no IL, while lower for  $\text{NiO}_x$ . The fixed charge density for an IL shows a positive correlation with the IL dipole density, suggesting that the fixed charge is related to the unbalanced IL dipole. Furthermore, using the conductance method, we find a low trap density of the  $\text{Al}_2\text{O}_3$ /IL/AlGaIn interface for  $\text{AlO}_x$  and  $\text{NiO}_x$  ILs, in comparison with that of the  $\text{Al}_2\text{O}_3$ /AlGaIn interface with no IL.

**Keywords:** AlGaIn/GaN device, interfacial layer, threshold voltage control, vacuum level step, fixed charge